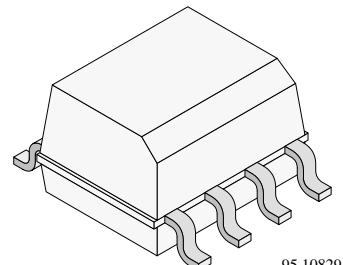


Surface Mount Optocoupler with Phototransistor Output

Order Nos. and Classification table is on sheet 2.

Description

The TCMT1020 series consists of a gallium arsenid infrared-emitting diode, optically coupled to a silicon NPN epitaxial planar transistor in an 8-lead SOIC package (small outline).



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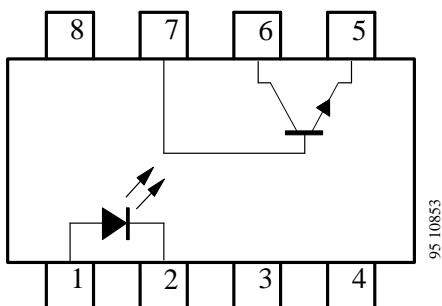
Applications

- Computer peripheral interface
- Microprocessor system interface
- Hybride substrates that require high density mounting
- DC/DC converter

Features

- Current Transfer Ratio (CTR) selected into 4 groups, specified at $I_F = 10 \text{ mA}$
- Test isolation voltage between input and output $V_{IO} (\text{RMS})$: 2.5 kV
- 8-lead package, similar to SOIC-8
- Minimum $V_{(BR)\text{CEO}}$ of 90 V guaranteed
- Suitable for cleaning process without chemical solvent
- Soldering methods according to CECC 00802 table 1, class B or C
- Low temperature coefficient of CTR
- Base connected
- Underwriters Laboratory (UL) recognized-file No. E-76222

Pin Connection



Order Schematic

Part Numbers	CTR-Ranking
TMCT1020/ TCMT1020-GS12	>40%
TMCT1021/ TCMT1021-GS12	40 to 80%
TMCT1022/ TCMT1022-GS12	65 to 125%
TMCT1023/ TCMT1023-GS12	100 to 200%
TMCT1024/ TCMT1024-GS12	160 to 320%

Prefix: GS12 = Taped and reeled version

Absolute Maximum Ratings

Input (Emitter)

Parameters	Test Conditions	Symbol	Value	Unit
Reverse voltage		V _R	5	V
Forward current		I _F	60	mA
Forward surge current	t _p ≤ 10 µs	I _{FSM}	3	A
Power dissipation	T _{amb} ≤ 25°C	P _{tot}	100	mW
Junction temperature		T _j	125	°C

Output (Detector)

Parameters	Test Conditions	Symbol	Value	Unit
Collector base voltage		V _{CBO}	90	V
Collector emitter voltage		V _{CEO}	90	V
Emitter collector voltage		V _{ECO}	7	V
Collector current		I _C	50	mA
Collector peak current	t _p /T = 0.5, t _p ≤ 10 ms	I _{CM}	100	mA
Power dissipation	T _{amb} ≤ 25°C	P _{tot}	150	mW
Junction temperature		T _j	125	°C

Coupler

Parameters	Test Conditions	Symbol	Value	Unit
AC isolation test voltage (RMS)		V _{IO} ¹⁾	2.5	kV
Total power dissipation	T _{amb} ≤ 25°C	P _{tot}	250	mW
Ambient temperature range		T _{amb}	-55 to +100	°C
Storage temperature range		T _{stg}	-55 to +125	°C
Soldering classification	Single wave, t ≤ 10 s	T _{sd}	260	°C

1) Related to standard climate 23/50 DIN 50014

Electrical Characteristics

$T_{amb} = 25^\circ\text{C}$

Input (Emitter)

Parameters	Test Conditions	Type	Symbol	Min.	Typ.	Max.	Unit
Forward voltage	$I_F = 50 \text{ mA}$		V_F		1.25	1.6	V
Breakdown voltage	$I_R = 100 \mu\text{A}$		$V_{(BR)}$	5			V
Junction capacitance	$V_R = 0, f = 1 \text{ MHz}$		C_j		50		pF

Output (Detector)

Parameters	Test Conditions	Type	Symbol	Min.	Typ.	Max.	Unit
Collector base breakdown voltage	$I_C = 100 \mu\text{A}$		$V_{(BR)CB0}$	90			V
Collector emitter breakdown voltage	$I_C = 1 \text{ mA}$		$V_{(BR)CEO}$	90			V
Emitter collector breakdown voltage	$I_E = 100 \mu\text{A}$		$V_{(BR)ECO}$	7			V
Collector emitter cut-off current	$V_{CE} = 10 \text{ V}, I_F = 0$		I_{CEO}			50	nA

Coupler

Parameters	Test Conditions	Type	Symbol	Min.	Typ.	Max.	Unit
AC isolation test voltage (RMS)	$f = 50 \text{ Hz}, t = 1 \text{ s}$		V_{IO}	2.5			kV
Collector emitter saturation voltage	$I_F = 10 \text{ mA}, I_C = 1 \text{ mA}$		V_{CEsat}			0.3	V
Cut-off frequency	$V_{CE} = 5 \text{ V}, I_F = 10 \text{ mA}, R_L = 100 \Omega$		f_C		110		kHz
Coupling capacitance	$f = 1 \text{ MHz}$		C_k		0.3		pF

Current Transfer Ratio (CTR)

Parameters	Test Conditions	Type	Symbol	Min.	Typ.	Max.	Unit
I_C/I_F	$V_{CE} = 5 \text{ V}, I_F = 10 \text{ mA}$	TCMT1020 TCMT1021 TCMT1022 TCMT1023 TCMT1024	CTR	0.2 0.4 0.65 1 1.6		0.8 1.25 2 3.2	

TCMT1020 Series

TEMIC
Semiconductors

Switching Characteristics (Typical Values)

$V_S = 5 \text{ V}$

Type	$R_L = 100 \Omega$ (see figure 1)						
	$t_d[\mu\text{s}]$	$t_f[\mu\text{s}]$	$t_{on}[\mu\text{s}]$	$t_s[\mu\text{s}]$	$t_f[\mu\text{s}]$	$t_{off}[\mu\text{s}]$	$I_C[\text{mA}]$
TCMT1020/ TCMT1020-GS12	>0.70	>1.35	>1.70	>0.15	>1.35	>1.50	5
TCMT1021/ TCMT1021-GS12	0.70	1.35	1.70	0.15	1.35	1.50	5
TCMT1022/ TCMT1022-GS12	1.20	190	2.80	0.20	1.90	2.10	5
TCMT1023/ TCMT1023-GS12	1.60	2.90	4.10	0.30	2.90	3.20	5
TCMT1024/ TCMT1024-GS12	2.20	4.80	5.90	0.40	4.80	5.20	5

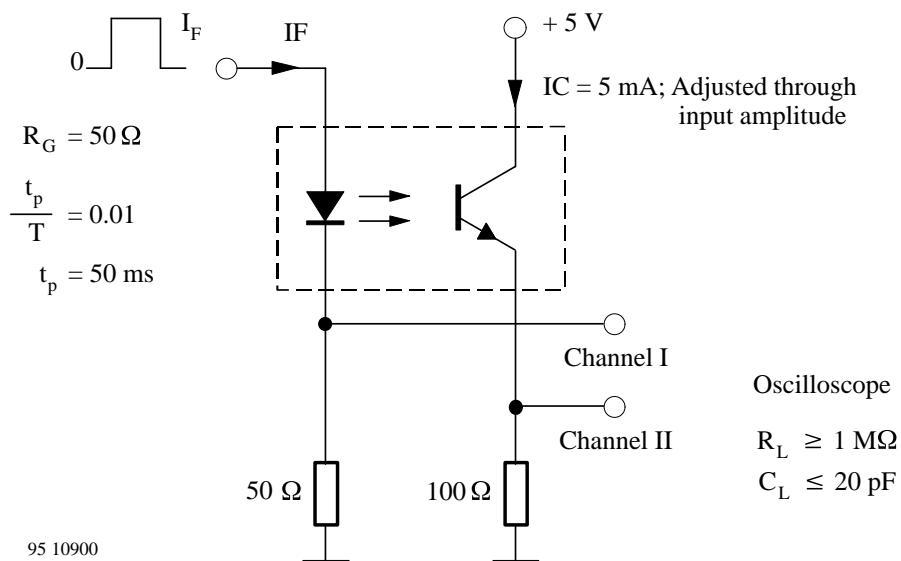


Figure 1. Test circuit, non-saturated operation

Typical Characteristics ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

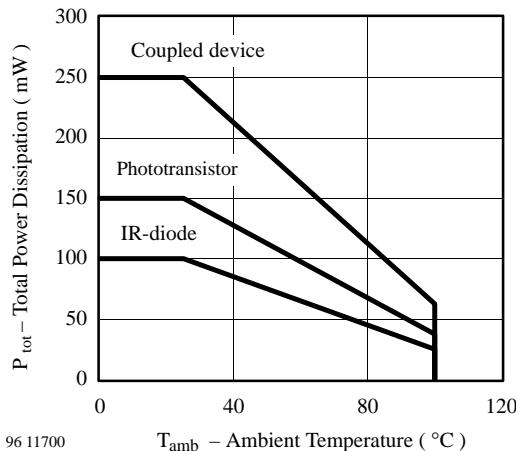


Figure 1. Total Power Dissipation vs. Ambient Temperature

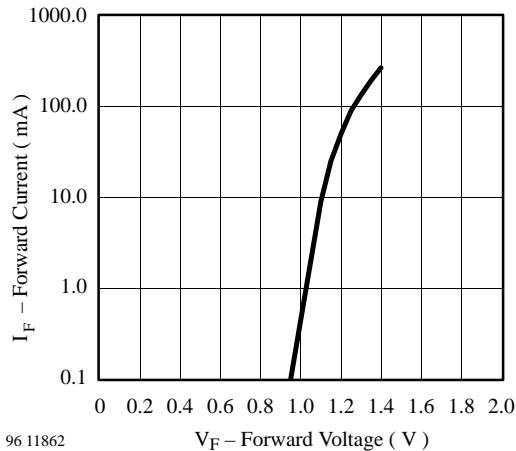


Figure 2. Forward Current vs. Forward Voltage

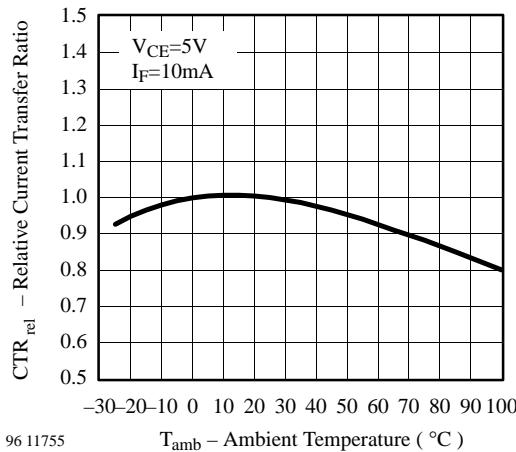


Figure 3. Rel. Current Transfer Ratio vs. Ambient Temp.

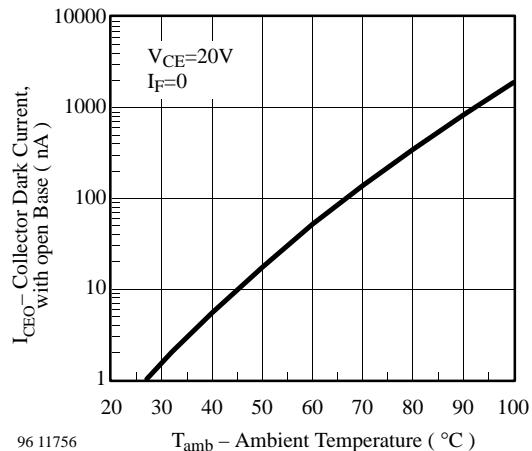


Figure 4. Collector Dark Current vs. Ambient Temperature

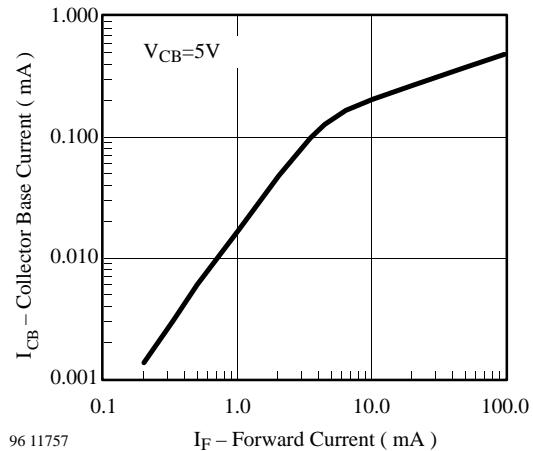


Figure 5. Collector Base Current vs. Forward Current

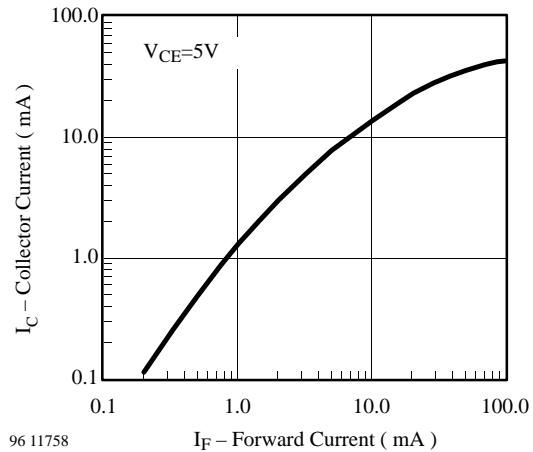


Figure 6. Collector Current vs. Forward Current

TCMT1020 Series

TEMIC
Semiconductors

Typical Characteristics ($T_{amb} = 25^{\circ}\text{C}$, unless otherwise specified)

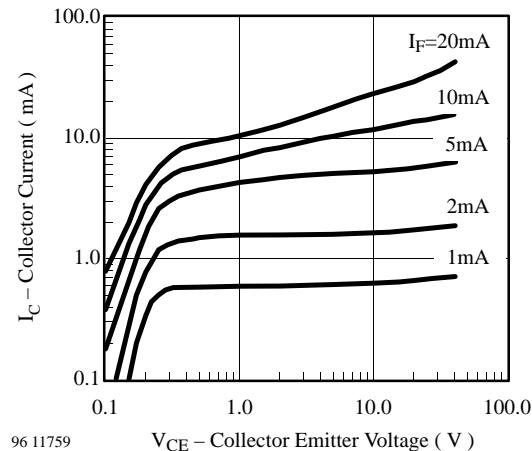


Figure 7. Collector Current vs. Collector Emitter Voltage

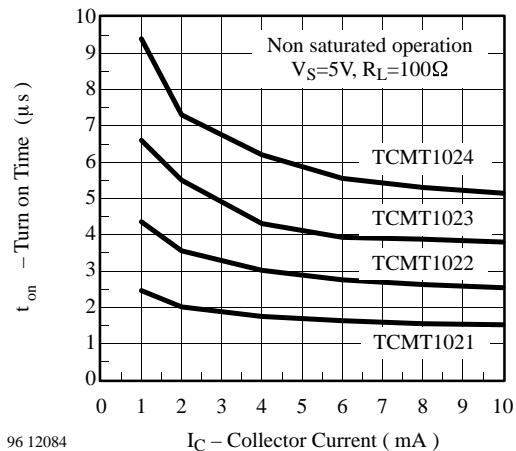


Figure 10. Turn on Time vs. Collector Current

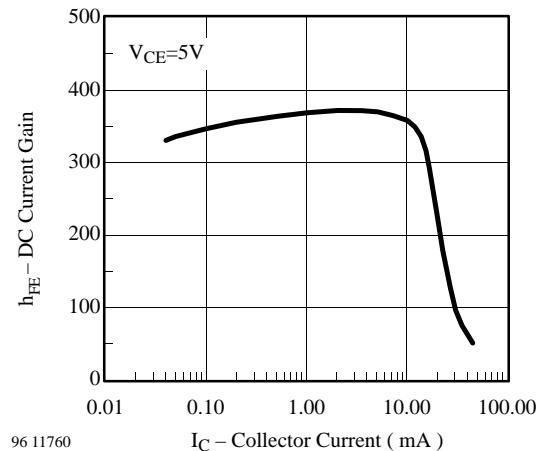


Figure 8. DC Current Gain vs. Collector Current

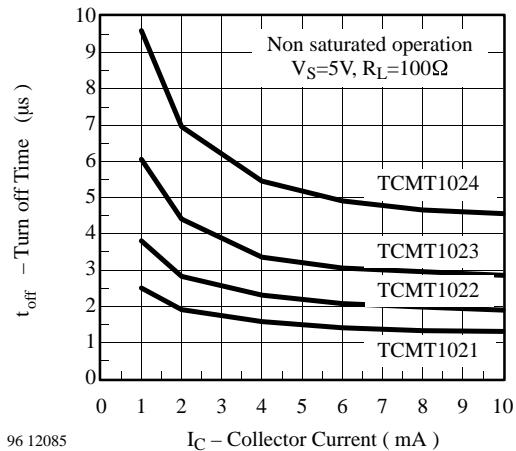


Figure 11. Turn off Time vs. Collector Current

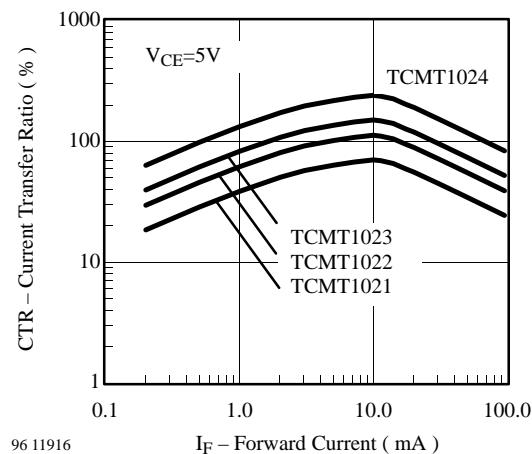
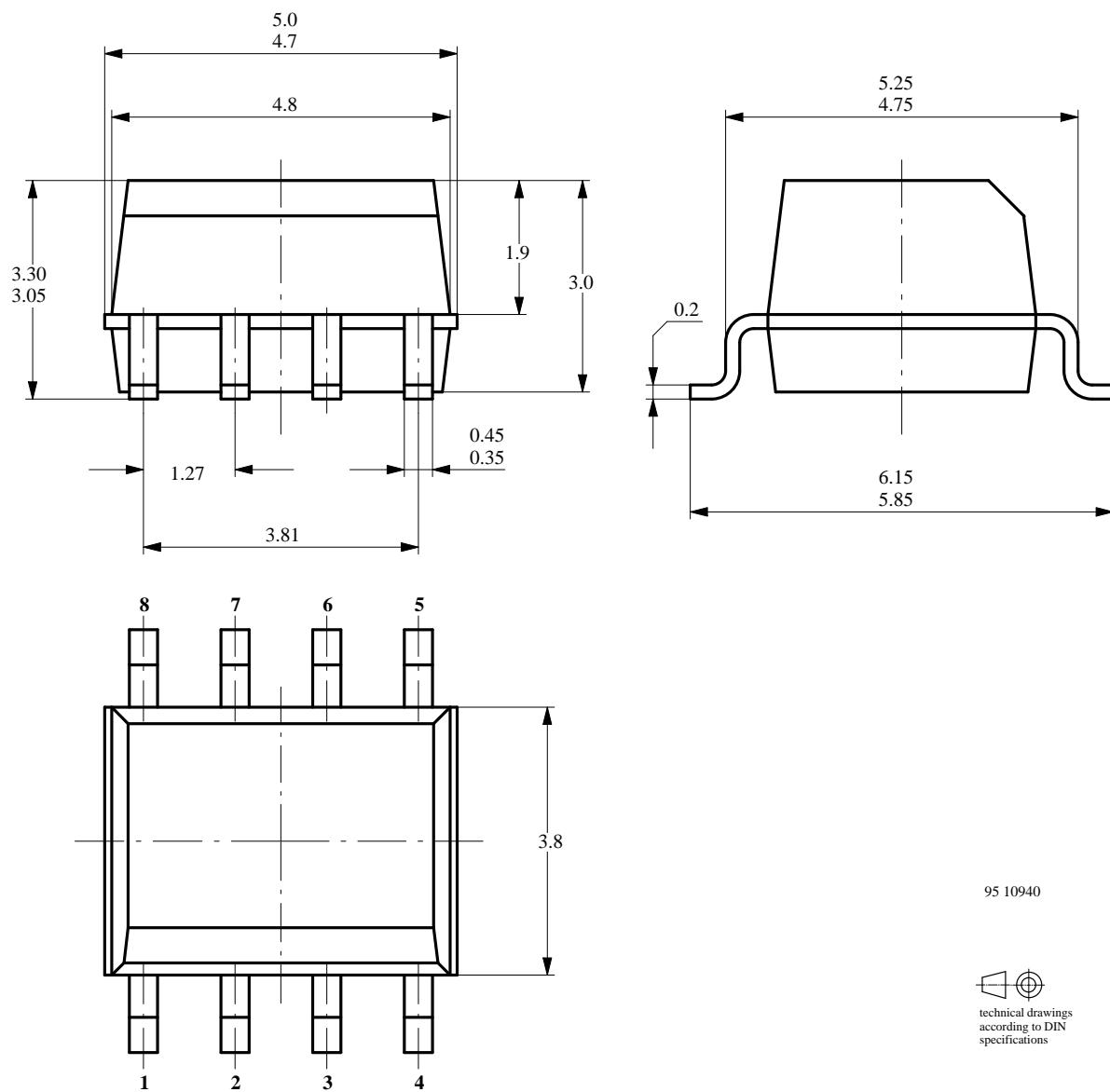


Figure 9. Current Transfer Ratio vs. Forward Current

Dimensions in mm



Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany
Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423